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APPLICANT : TANAKA KIKINZOKU KOGYO KK;

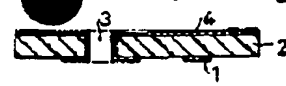
INVENTOR : ONODERA TAMOTSU;

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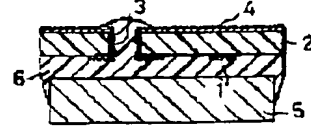
TITLE : MANUFACTURE OF METALLIC BASE
SUBSTRATE

AF

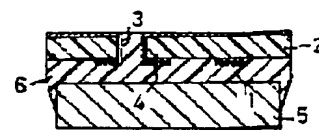
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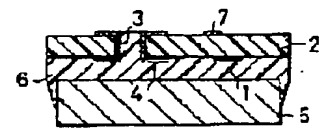
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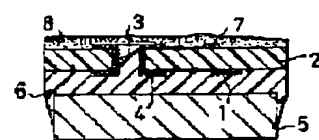
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(d)



(e)



ABSTRACT : PURPOSE: To prevent a black treated surface and void from remaining and a circuit from bending.

CONSTITUTION: When a double-sided printed wiring board with a through-holes for improving heat dissipation property, etc., is manufactured by using a metallic plate 5, black treatment is performed after pattern formation on one side of a double-sided copper clad board. After a metallic plate is laminated and formed in the one surface wherein pattern formation is performed with a bonding layer 6 between, the other side of the double-sided copper clad board is mechanically polished and solder resist 8 is applied to the other side after performing pattern formation for it. Thereby, firm polishing is possible during mechanical polishing and mechanical strength of the other side is improved during lamination formation.

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